Artificial Intelligence-Based Technologies for Telecom and Sensing Systems

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Deadline for manuscript submissions:
closed (30 June 2021)

Message from the Guest Editors

Dear Colleagues,

Artificial Intelligence (AI) is an emerging hot topic in the research on telecom and sensor systems, which we can use to design intelligent tools superior to human capacity intelligence processing. With the progress in computer science, AI is being progressively applied to all aspects of human life, from fundamental points like health and safety to food or hygiene. Currently, many AI-related technologies have come out of the laboratory and have made advances in many fields of application. Furthermore, data analysis techniques which assist in the detection and interpretation of information hidden in the data are widely used in several scientific fields. This SI will be dedicated to progress, challenges, and current status in AI-related technologies for telecom and sensor systems. The requested research articles, including review articles, should be related to AI technologies. High-quality manuscript submissions describing future advances or ongoing work are welcome.

Special Issue

Editor-in-Chief

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Message from the Editor-in-Chief

I would like to introduce the new, online, and open access journal *Telecom*. The purpose of *Telecom* is to publish high-quality research papers as well as review articles that address recent advances in communications technology. We invite researchers to contribute original papers describing applications and experiences in emerging trends of all fields of telecommunications engineering. *Telecom* also welcomes Special Issue proposals from academics and industrial researchers. We aim to facilitate more collaboration between scientists and engineers around the world, such that they will produce their innovative ideas and submit their cutting-edge technologies to *Telecom*. We anticipate the receipt of your contributions to *Telecom*, and we welcome your comments and ideas on how to improve this journal.

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